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## 5 **PLDM Accelerator Modeling**

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152

## Foreword

153 The *PLDM Accelerator Modeling* (DSP2061) document was prepared by the Platform Management  
154 Communications Infrastructure (PMCI) Working Group of the DMTF.

155 DMTF is a not-for-profit association of industry members dedicated to promoting enterprise and systems  
156 management and interoperability. For information about the DMTF, see <https://www.dmtf.org>.

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172

## Introduction

173 This document describes a modeling scheme for an Accelerator card using PLDM for Platform Monitoring  
174 and Control [DSP0248](#) semantics.

### 175 Document conventions

#### 176 Typographical conventions

177 The following typographical conventions are used in this document:

- 178 • Document titles are marked in *italics*.
- 179 • Important terms that are used for the first time are marked in *italics*.
- 180 • Terms include a link to the term definition in the “Terms and definitions” clause, enabling easy  
181 navigation to the term definition.
- 182 • ABNF rules are in `monospaced font`.

#### 183 ABNF usage conventions

184 Format definitions in this document are specified using ABNF (see [RFC5234](#)), with the following  
185 deviations:

- 186 • Literal strings are to be interpreted as case-sensitive Unicode characters, as opposed to the  
187 definition in [RFC5234](#) that interprets literal strings as case-insensitive US-ASCII characters.

#### 188 Reserved and unassigned values

189 Unless otherwise specified, any reserved, unspecified, or unassigned values in enumerations or other  
190 numeric ranges are reserved for future definition by the DMTF.

191 Unless otherwise specified, numeric or bit fields that are designated as reserved shall be written as 0  
192 (zero) and ignored when read.

#### 193 Byte ordering

194 Unless otherwise specified, byte ordering of multibyte numeric fields or bit fields is “Big Endian” (that is,  
195 the lower byte offset holds the most-significant byte, and higher offsets hold less-significant bytes).

#### 196 Other Conventions

197 See ANNEX A for other conventions



## 198 1 Scope

199 This document defines an example data model for implementing the systems management of  
200 accelerators using PLDM for Platform Monitoring and Control [DSP0248](#) semantics. This document  
201 establishes a common framework that can provide implementation consistency between a system's  
202 Management Controller and accelerators and accelerator cards the system contains, focusing on FPGAs  
203 and GPUs and similar devices that offload processing from the host CPU. This data model is assumed to  
204 be extensible to a variety of physical implementations and should not be construed to be limited to the  
205 examples herein.

206 Accelerators and Accelerator card implementations may include ancillary features such as networking  
207 and storage that have management schemas defined in other data models and Specifications. The  
208 management of those features is outside the scope of this data model. The data model provided here  
209 focuses on the management of the accelerator features of the card, but composite sensors that return  
210 overall card status for example, may include metadata from those other functional areas. For instance, it  
211 may be appropriate to use either [DSP2054](#) or [DSP0222](#) for the management of networking features that  
212 may be included on the accelerator or card.

## 213 2 Normative references

214 The following referenced documents are indispensable for the application of this document. For dated or  
215 versioned references, only the edition cited (including any corrigenda or DMTF update versions) applies.  
216 For references without a date or version, the latest published edition of the referenced document  
217 (including any corrigenda or DMTF update versions) applies. Unless otherwise specified, for DMTF  
218 documents this means any document version that has minor or update version numbers that are later  
219 than those for the referenced document. The major version numbers must match the major version  
220 number given for the referenced document.

221 DMTF DSP0222, Network Controller Sideband Interface (NC-SI) Specification 1.1,  
222 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0222\\_1.1.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0222_1.1.0.pdf)

223 DMTF DSP0236, *MCTP Base Specification 1.3*,  
224 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0236\\_1.3.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0236_1.3.0.pdf)

225 DMTF DSP0240, *Platform Level Data Model (PLDM) Base Specification 1.1*,  
226 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0240\\_1.1.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0240_1.1.0.pdf)

227 DMTF DSP0241, *Platform Level Data Model (PLDM) Over MCTP Binding Specification 1.0*,  
228 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0241\\_1.0.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0241_1.0.0.pdf)

229 DMTF DSP0245, *Platform Level Data Model (PLDM) IDs and Codes Specification 1.3*,  
230 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0245\\_1.3.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0245_1.3.0.pdf)

231 DMTF DSP0248, *Platform Level Data Model (PLDM) for Platform Monitoring and Control Specification*  
232 *1.2*, [https://www.dmtf.org/sites/default/files/standards/documents/DSP0248\\_1.2.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0248_1.2.0.pdf)

233 DMTF DSP0249, *Platform Level Data Model (PLDM) State Sets Specification 1.1*,  
234 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0249\\_1.1.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0249_1.1.0.pdf)

235 DMTF DSP0257, *Platform Level Data Model (PLDM) FRU Data Specification 1.0*,  
236 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0257\\_1.0.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0257_1.0.0.pdf)

237 DMTF DSP0267, *Platform Level Data Model (PLDM) for Firmware Update Specification 1.1*,  
238 [https://www.dmtf.org/sites/default/files/standards/documents/DSP0267\\_1.1.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP0267_1.1.0.pdf)

239 DMTF DSP2054, *Platform Level Data Model (PLDM) NIC Modeling Specification 1.0*,  
240 [https://www.dmtf.org/sites/default/files/standards/documents/DSP2054\\_1.0.0.pdf](https://www.dmtf.org/sites/default/files/standards/documents/DSP2054_1.0.0.pdf)

- 241 IETF RFC2781, *UTF-16, an encoding of ISO 10646*, February 2000,  
242 <https://www.ietf.org/rfc/rfc2781.txt>
- 243 IETF STD63, *UTF-8, a transformation format of ISO 10646* <https://www.ietf.org/rfc/std/std63.txt>
- 244 IETF RFC4122, *A Universally Unique Identifier (UUID) URN Namespace*, July 2005,  
245 <https://www.ietf.org/rfc/rfc4122.txt>
- 246 IETF RFC4646, *Tags for Identifying Languages*, September 2006,  
247 <https://www.ietf.org/rfc/rfc4646.txt>
- 248 ISO 8859-1, *Final Text of DIS 8859-1, 8-bit single-byte coded graphic character sets — Part 1: Latin  
249 alphabet No. 1*, February 1998
- 250 ISO/IEC Directives, Part 2, *Rules for the structure and drafting of International Standards*,  
251 <https://www.iso.org/sites/directives/current/part2/index.xhtml>
- 252 IETF RFC5234, *ABNF: Augmented BNF for Syntax Specifications, January 2008*,  
253 <https://tools.ietf.org/html/rfc5234>

### 254 **3 Terms and definitions**

255 In this document, some terms have a specific meaning beyond the normal English meaning. Those terms  
256 are defined in this clause.

257 The terms “shall” (“required”), “shall not”, “should” (“recommended”), “should not” (“not recommended”),  
258 “may”, “need not” (“not required”), “can” and “cannot” in this document are to be interpreted as described  
259 in [ISO/IEC Directives, Part 2](#), Clause 7. The terms in parentheses are alternatives for the preceding term,  
260 for use in exceptional cases when the preceding term cannot be used for linguistic reasons. Note that  
261 [ISO/IEC Directives, Part 2](#), Clause 7 specifies additional alternatives. Occurrences of such additional  
262 alternatives shall be interpreted in their normal English meaning.

263 The terms “clause”, “subclause”, “paragraph”, and “annex” in this document are to be interpreted as  
264 described in [ISO/IEC Directives, Part 2](#), Clause 6.

265 The terms “normative” and “informative” in this document are to be interpreted as described in [ISO/IEC  
266 Directives, Part 2](#), Clause 3. In this document, clauses, subclauses, or annexes labeled “(informative)” do  
267 not contain normative content. Notes and examples are always informative elements.

268 Refer to [DSP0240](#) for terms and definitions that are used across the PLDM specifications.

## 269 **4 Symbols and abbreviated terms**

270 Refer to [DSP0240](#) and [DSP0248](#) for symbols and abbreviated terms that are used across the PLDM  
271 specifications. For the purposes of this document, the following additional symbols and abbreviated terms  
272 apply.

### 273 **4.1**

#### 274 **PCB**

275 Printed Circuit Board

### 276 **4.2**

#### 277 **FPGA**

278 Field Programmable Gate Array

### 279 **4.3**

#### 280 **GPU**

281 Graphics Processing Unit

## 282 5 PLDM Accelerator Modeling overview

### 283 5.1 General

284 This document describes a hierarchical modeling scheme for an Accelerator card using PLDM for  
285 Platform Monitoring and Control [DSP0248](#) semantics. The model is scalable, allowing consistent  
286 modeling of Accelerator cards with different configuration options such as the number of Accelerators.

287 While PLDM for Platform Monitoring and Control [DSP0248](#) is a published standard, using the model  
288 defined in this document simplifies interoperability by establishing a consistent schema.

289 The basic format that is used for sending PLDM messages is defined in [DSP0240](#). The format that is  
290 used for carrying PLDM messages over a transport-layer protocol and medium is given in companion  
291 documents to the base specification. For example, [DSP0241](#) defines how PLDM messages are formatted  
292 and sent using MCTP as the transport.

293 The model supports the following:

- 294 • Consistent modeling of an Accelerator card regardless of the specific configuration and resource  
295 count
- 296 • Accelerator card hardware structure description
- 297 • Reporting of configuration changes such as firmware update

### 298 5.2 Model elements

#### 299 5.2.1 PLDM terminus

300 PLDM for Platform Monitoring and Control [DSP0248](#) defines a single root for every device instance,  
301 referred to as PLDM Terminus and identified with a TID. The term “MC” is used to identify a PLDM  
302 terminus which communicates with an Accelerator card throughout this document.

303 When there are multiple Accelerators assembled on the same card, there may be a single Accelerator  
304 which reports all the sensors of all the elements on the Accelerator card to the MC. Alternatively, each  
305 Accelerator in the Accelerator card may present a separate PLDM terminus.

306 PLDM for Platform Monitoring and Control [DSP0248](#) does not allow associating components reported via  
307 different PLDM termini since every database is relative to a given PLDM terminus. To overcome this  
308 constraint, the implementers can retrieve a globally unique ID (Board part number and serial number)  
309 from each TID and recognize these TIDs belonging to the same Accelerator card. The process to retrieve  
310 the globally unique ID (Board part number and serial number) from each TID is outside of this document.

311 All PLDM IDs specified by the model in this document shall be consistent across all TIDs on a given card.  
312 This avoids conflict from duplication of IDs in the combined model, generated by merging the TID-specific  
313 model elements reported as part of the overall model.

#### 314 5.2.2 Accelerator card

315 In this model, the Accelerator card is the top-level element of the hierarchy containing one or more  
316 Accelerators on a PCB. An Accelerator card is a hardware and software solution that offloads certain  
317 processing from the host processor. The Accelerator card in this document refers to various form factors  
318 and is represented with PLDM Entity ID code 68 for Add-in card. The Accelerator card may contain  
319 sensors.

#### 320 5.2.3 Accelerator

321 In this model, an Accelerator is the second level element of the hierarchy containing one or more sensors.  
322 An Accelerator is a hardware device with a main function of offloading certain processing from the host

323 processor. An Accelerator may contain sensors such as health state, power-consumption, and  
 324 temperature.

325 **5.2.4 Memory**

326 The term “memory” in this document covers the internal memory of the Accelerator, memory chips  
 327 installed on the PCB, and the DIMMs. In this model, the memory is at the second level of the hierarchy. A  
 328 Memory may contain sensors such as temperature, health state, and error statistics.

329 **5.2.5 Inter-Accelerator card connection**

330 The Accelerator cards may support communication with each other. Figure 1 depicts an Inter-Accelerator  
 331 card connection, and it may not be the only communication interface between Accelerator cards.

332

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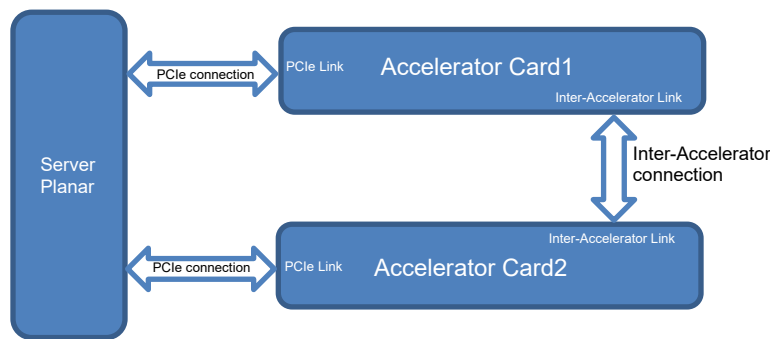
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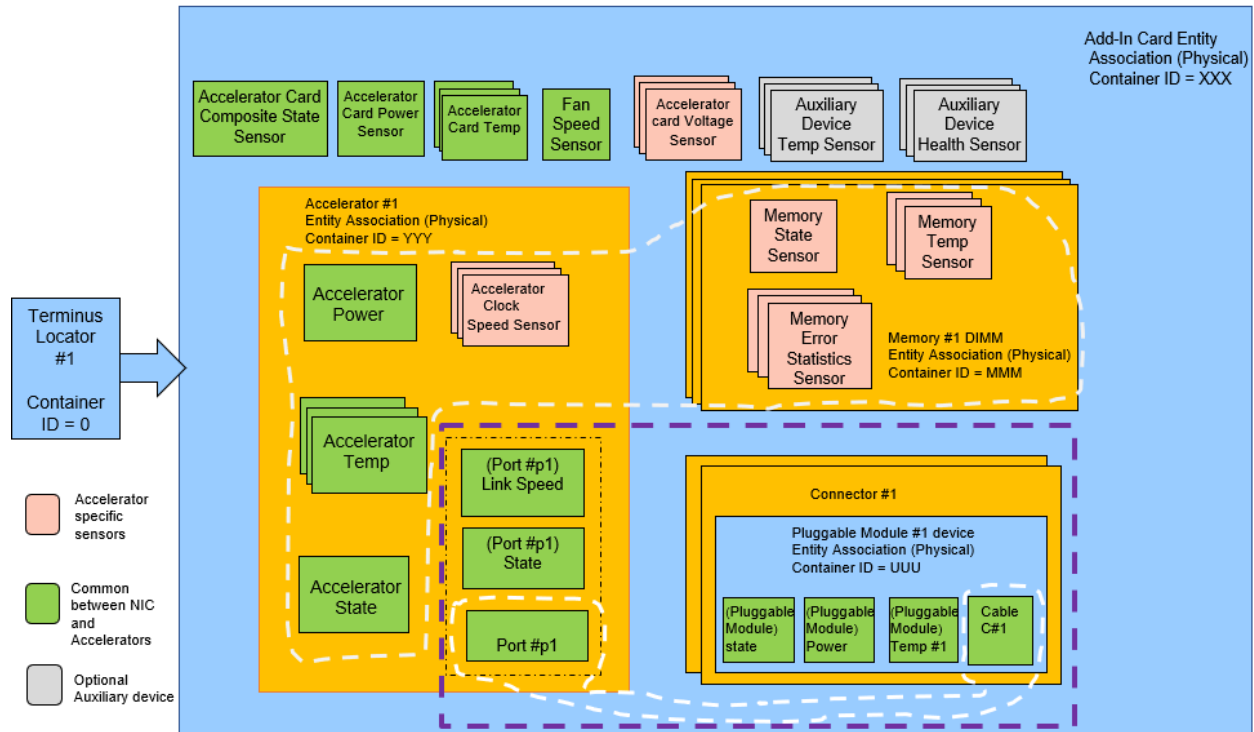
**Figure 1 – Inter-Accelerator card connection**

342 **5.3 Model sensors**

343 **5.3.1 General**

344 Attributes are reported by means of sensors. Numeric sensors are used to report specific measured  
 345 attributes. State sensors report operational and/or health state. The default thresholds for all numeric  
 346 sensors shall be set by the hardware vendor. The sensors can be associated with any entity such as the  
 347 Accelerator card, Accelerator or Memory. The description of each sensor is applicable only for the  
 348 implemented sensors and it is not mandatory to implement all the sensors described in this document.  
 349 There may be auxiliary devices present on the accelerator card and each auxiliary device may present its  
 350 own set of sensors.

351 Note: The Sensor Auxiliary Names PDR is recommended to provide the proper name of each sensor.



352

353

Figure 2 – Accelerator card PLDM model diagram

354 **5.3.2 Accelerator card temperature sensor**

355 The temperature sensor on the Accelerator card reports the card's ambient temperature and is  
 356 represented using a numeric sensor. There may be multiple temperature sensors installed on the  
 357 Accelerator card.

358 **5.3.3 Accelerator card power sensor**

359 The power sensor on the Accelerator card reports the estimated or measured aggregate power  
 360 consumption of the Accelerator card and is represented using a numeric sensor. An Accelerator card  
 361 which cannot accurately report its real-time power consumption may report its estimated maximal power.  
 362 When there are multiple Accelerators on the same Accelerator card, there may be no visibility by any  
 363 Accelerator to the real-time information of the other Accelerators. For this reason, this sensor is only  
 364 implemented when there is only one Accelerator on the Accelerator card, or when there is a hardware  
 365 sensor which does allow measuring and reporting the total card power consumption or when the maximal  
 366 estimated power is reported without being measured or when the accelerators can communicate with  
 367 each other.

368 **5.3.4 Accelerator card fan speed sensor**

369 The fan speed sensor on the Accelerator card reports the speed of an active cooling fan and is  
 370 represented using a numeric sensor. An Accelerator card may have multiple fans installed, each  
 371 potentially with its own speed sensor.

372 **5.3.5 Accelerator card voltage sensor**

373 The voltage sensors on the Accelerator card report various voltages on the card and are represented  
 374 using numeric sensors. There may be multiple voltage sensors installed on the card.

### 375 **5.3.6 Accelerator card auxiliary device temperature sensor**

376 The temperature sensor on the auxiliary device reports the ambient temperature of the auxiliary device  
377 and is represented using a numeric sensor. This document does not mandate having an auxiliary device  
378 temperature sensor.

### 379 **5.3.7 Accelerator card auxiliary device health sensor**

380 The health sensor on the auxiliary device reports the health state of the auxiliary device and is  
381 represented using a state sensor. This document does not mandate having an auxiliary device health  
382 sensor.

### 383 **5.3.8 Accelerator card composite state sensor**

384 The Accelerator card composite state sensor combines the Accelerator card thermal state sensor, the  
385 Memory operational fault state sensor, and the Accelerator card health state sensor. The Accelerator card  
386 health state is the aggregated health state of all the components on the card. The reported aggregated  
387 health state of the Accelerator card reflects the worst case of the reported health states for each of the  
388 elements monitored in the model. For example, if an Accelerator health state is non-critical and a memory  
389 health state is critical, then the Accelerator card health state may be set to critical in the Accelerator card  
390 composite state sensor.

391 When there are multiple Accelerators, there may be no visibility by any Accelerator to the real-time  
392 information of other Accelerators. For this reason, this composite state sensor is only implemented when  
393 there is only a single Accelerator on the Accelerator card or when the Accelerator card has the needed  
394 visibility of all the components such as Accelerators and memory.

395 To determine the respective sensor states, the following steps shall be used: the accelerator card thermal  
396 state sensor shall also reflect the auxiliary device temperature and the accelerator card health state  
397 sensor shall also reflect the auxiliary device health state.

### 398 **5.3.9 Accelerator temperature sensor**

399 The temperature sensor of the Accelerator reflects the device temperature and is represented using a  
400 numeric sensor. This sensor is typically located in the thermally sensitive areas on the Accelerator.

### 401 **5.3.10 Accelerator power sensor**

402 The power sensor on the Accelerator reports the estimated or measured power consumption of the  
403 Accelerator and represented using a numeric sensor. An Accelerator which cannot accurately report its  
404 real-time power consumption may report its estimated maximal power.

### 405 **5.3.11 Accelerator composite state sensor**

406 The Accelerator composite state sensor combines the Accelerator Thermal trip state, Accelerator health  
407 state, Configuration valid state, Configuration change state, and Accelerator firmware version change  
408 state. The MC can use this sensor to identify issues with the Accelerator and to identify the specific  
409 maintenance operations that it needs to perform. These operations may include Accelerator reset,  
410 system-level shutdown for thermal protection, and other system-level maintenance.

411  
412 Using the configuration change indication, the Accelerator notifies the MC to retrieve PDRs updated by  
413 the configuration change.

414 When a firmware update is detected, the composite state sensor can reflect this event to the MC, allowing  
415 the MC to take any action needed to respond to the update. Note that reading the new firmware version  
416 may be performed by the MC using protocols other than PLDM for Platform Monitoring and Control  
417 [DSP0248](#), such as [DSP0257](#) and/or [DSP0267](#). Please note that firmware update only reflects the

418 conclusion of the firmware programming operation; it is device-specific whether this detection additionally  
419 implies that new firmware is already active.

### 420 **5.3.12 Accelerator clock speed sensor**

421 The clock speed sensor of the Accelerator is used to read the clock speed and is represented using  
422 numeric sensors. An Accelerator may have multiple clock domains, each with its own clock speed sensor

### 423 **5.3.13 Memory temperature sensor**

424 The temperature sensors on the memory modules and internal memory report the memory temperatures  
425 and are represented using numeric sensors. There may be multiple memory temperature sensors  
426 installed on the internal memory, on the soldered memory, and on the DIMMs.

427 The memory that is soldered on the Accelerator card PCB may not have a temperature sensor on them.  
428 In this case, the implementations may choose to have a temperature sensor near the soldered memory  
429 chips calibrated to approximate the temperature of those memory devices.

### 430 **5.3.14 Memory error statistics**

431 The memory error statistics sensors report the memory error statistics (i.e., correctable errors and  
432 uncorrectable errors) and are represented using numeric sensors. Refer to the “sensorUnits enumeration”  
433 table in [DSP0248](#).

### 434 **5.3.15 Memory composite state sensor**

435 The memory composite state sensor combines sensors such as memory health state sensor, memory  
436 cache state sensor, memory error state sensor, and memory redundant activity state sensor. The MC can  
437 use this sensor to identify issues with the memory and to identify the specific maintenance operations that  
438 it needs to perform. Refer to Table 11 (Memory-Related State Sets) of [DSP0249](#) for all memory-related  
439 sensors and their states.

## 440 **5.4 Hierarchy description of the Accelerator card model elements**

### 441 **5.4.1 General**

442 PLDM Accelerator Modeling uses a hierarchical model. Refer to section 10 PLDM associations and  
443 section 11 Entity Association PDR of [DSP0248](#) to understand physical and logical associations.

### 444 **5.4.2 Physical entities association**

445 Physical association is defined in [DSP0248](#) as a method to associate components which are physically  
446 connected to each other. The model uses this concept to describe the following structures:

- 447 • Content of the Accelerator card PCB
- 448 • Content of the Accelerators
- 449 • Content of the Memory Modules

450 A hierarchy entity is defined using an entity association PDR identified with a unique **containerID**  
451 identifier parameter. The entity association PDR’s **containerEntityContainerID** references the PDR in  
452 which the entity is contained. This entity association PDR shall also contain the contained entities defined  
453 in [DSP2054](#) for the elements shown inside the purple dotted line of Figure 2.

454 Figure 3 shows an example of how an Accelerator card entity association PDR references its container  
455 entity and contained entities:



456

Accelerator card Entity Association PDR		
Container ID	100	
Record Handle	1100	
Container Entity		
Entity Type	68	Add-in card
Entity Instance Number	1	
Container Entity Container ID	0	System
Association Type	<b>Physical to Physical containment</b>	
Contained Entity - Accelerator		
Entity Type	149	Accelerator
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card
Contained Entity - Memory		
Entity Type	66	Memory
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

457  
458  
459

**Figure 3 – Hierarchy description using containerEntityContainerID referencing the containedEntityContainerID**

460

### 461 5.4.3 Logical entity association

462 The [DSP0248](#) defines logical association as a method to associate components which collectively form a  
463 shared property yet are not physically part of the same component. This model uses logical association to  
464 describe the following structures:

465 Figure 4 shows logical association between an Accelerator and a memory module:

Channel #1 Entity Association PDR		
Container ID	900	
Record Handle	1180	
Container Entity		
Entity Type	79	Processor/memory module (processor and memory together on a module)
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card
Association Type		<b>Logical containment</b>
Contained Entity - Accelerator		
Entity Type	149	Accelerator
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card
Contained Entity - Memory Module		
Entity Type	66	Memory module
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

466  
467

**Figure 4 – Defining a logical association**

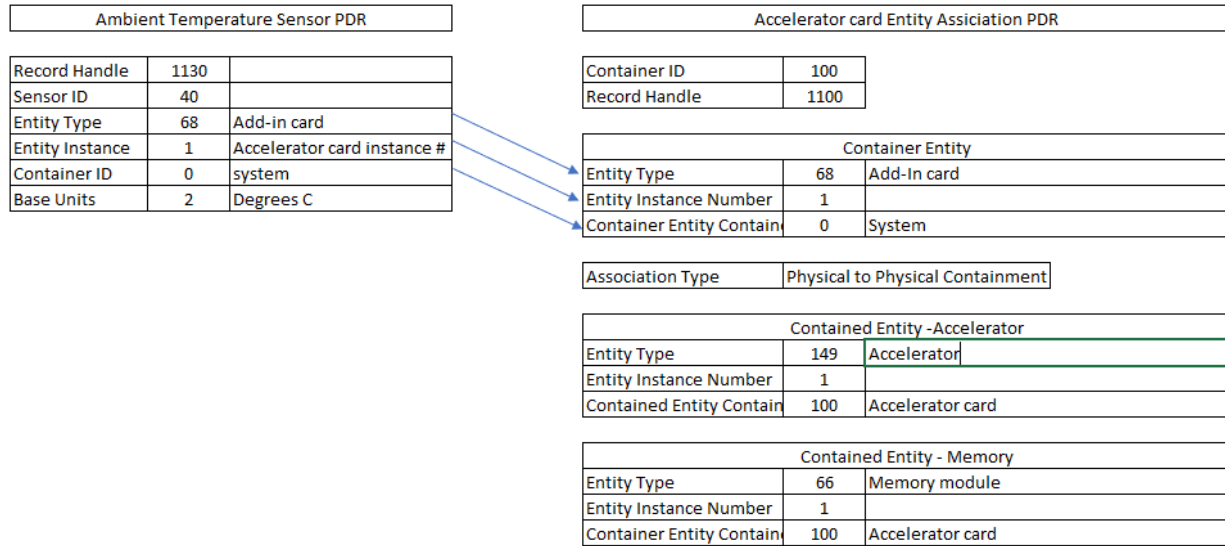
468 **5.4.4 Sensor association**

469 As per DSP0248, numeric and state sensors are not included inside entity association PDRs. They are  
470 instead associated to the measured entity by directly referencing the EntityContainerID, EntityType, and  
471 EntityInstanceNumber of the measured entity in an entity association PDR. A sensor is identified by a  
472 unique Sensor ID value.

473 **5.4.4.1 Associating a sensor at the top level**

474 When associating a sensor to the top-level entity which is the system the association uses the top-level  
475 **containerEntityType containerEntityInstanceNumber**, and **containerEntityContainerID** parameters.

476 Figure 5 illustrates the association of a temperature sensor to the Accelerator card in the model.



477

478

Figure 5 – Top-level sensor association

479 **5.5 Element PLDM Type IDs**

480 The model uses the following Type ID for each component in the model, selected from the available types  
 481 defined in [DSP0249](#). The following table lists the chosen Type IDs used in the model:

482

Table 1 – Type IDs used in the Accelerator card model

Component	Type ID
Accelerator card	68
Accelerator	149
Memory Module	66

483 **5.6 Enumeration**

484 **5.6.1 General**

485 PLDM for Platform Monitoring and Control [DSP0248](#) uses enumerated IDs to define elements in the  
 486 database. These IDs are labeled as:

- 487 • Container ID – unique for each container PDR in the model database
- 488 • Instance ID – unique for each entity type within a given hierarchy level
- 489 • Handle ID – unique ID for each PDR in the model database
- 490 • Sensor ID – unique for each sensor in the model database

491 The proposed model provides an example enumeration scheme for these IDs, allowing a reasonably  
 492 scalable formulation. This model is only an example and implementations should not rely on these values.

493 **5.6.2 Enumeration scheme**

494 The model assumes some maximal limits to define the enumerated values. These limits are provided as  
 495 an example and can be adjusted according to the specific Accelerator card requirements.

496 The example model enumeration is designed to support an Accelerator card that does not exceed the  
497 following limits:

498 **Table 2 – Chosen enumeration limits in the model**

Model Limit	Value
Max Accelerators	10
Max Memory Modules	10
Max board temperature sensors	10
Max temperature sensors per Accelerator	10

499

500 **Note:**

- 501 • If one of the above limits is insufficient for an Accelerator card, only the enumerated values will be  
502 affected and the model structure will not have to change.

503 Table 3 illustrates the enumeration scheme, calculated based on the above limits.

504

505

**Table 3 – Example Enumeration Scheme with Type IDs**

Item	Max count	Base Container	Max Container	Base Handle	Max Handle	Base Sensor-ID	Max Sensor-ID	Base Instance	Max instance	Type-ID
Accelerator card	1	100		1100				1	1	68
Accelerator card Composite State Sensor	1			1101	1101	5	5	1	1	68
Accelerator card Power Sensor	1			1102	1102	6	6	1	1	68
Accelerator card Temperature sensors	10			1130	1139	20	29	1	10	68
Accelerator card fan speed sensor	10			1150	1159	40	49	1	10	68
Accelerator card Voltage sensor	10			1170	1179	80	89	1	10	68
Processor Memory Interface	10	900	909	1180	1189	90	99	1	10	68
Connectors	20	1040	1059	1190	1209	100	119	1	20	185
Memory module	10	1020	1029	1210	1219			1	10	66
Memory composite state sensor	1			1220	1220	120	120		1	66
Memory temperature sensor	20			1225	1244	125	144	1	20	66
Memory module correctable Errors	10			1255	1264	150	159		1	66
Memory module uncorrectable Errors	10			1275	1284	180	189		1	66
Accelerators	10	1000	1009	1295	1304			1	10	149
Accelerator power sensor	1			1310	1310	210	210		1	149
Accelerator State sensor	1			1315	1315	220	220		1	149
Accelerator temperature sensor	10			1325	1334	240	249	1	10	149
Accelerator clock speed sensor	10			1335	1344	260	269	1	10	149
Accelerators Ports	10			1345	1354	290	299	1	10	149
Accelerators Port State	10			1360	1369	320	329	1	10	149
Accelerators Link Speed	10			1380	1389	350	359	1	10	149
Auxiliary Device Temp Sensor	1			1395	1395	380	380		1	68
Auxiliary Device health sensor	1			1400	1400	395	395		1	68
Plugs	20	1070	1089	1410	1429	410	429	1	20	214
Plug Composite Sensor	1			1430	1430	450	450	1	1	214
Plug Power Sensor	20			1440	1459	470	489	1	20	214
Plug Temp Sensor	10			1470	1479	510	519	1	10	214
Cable	16							1	16	187
Communication Channel	100	800	899	1490	1589			1	100	79

506

Calculated	Model Constant	Model Sensors described in this doc	Common sensors for NIC and Accelerator	n/a
------------	----------------	-------------------------------------	--	-----

## 507 5.7 Model illustration

### 508 5.7.1 General

509 The Accelerator card PLDM model is a hierarchical model. The following subclauses describe the model  
510 for each of the hierarchy levels:

### 511 5.7.2 Accelerator Card

512 The Accelerator card top level may contain the PCB card, Accelerators, Memory modules, one or more  
513 thermal sensors, Accelerator card composite state sensor, Fan speed sensor, power sensor and voltage  
514 sensors. The PCB power consumption is represented with a power sensor. The Accelerator card  
515 operational state is represented by a composite state sensor. When there are multiple Accelerators on  
516 the same card, Accelerator card sensors are typically only reported by the first Accelerator. The  
517 Accelerator card is responsible for determining the order of accelerators in the card. Note that the top-  
518 level health state sensor of the composite state sensor may reflect the card level sensors and the health  
519 states of Accelerators.

520 Refer the purple dotted line in Figure 2 to the Network port link speed sensor, Network port link state  
521 sensor, Pluggable module temperature sensor, pluggable module power sensor and Pluggable module  
522 composite state sensor sections of [DSP2054](#) specification for networking functionality.

### 523 5.7.3 Accelerator

524 The Accelerator hierarchy represents the active device (or one of multiple devices) that performs the  
525 Accelerator control interface. An Accelerator is represented as a collection of sensors.

### 526 5.7.4 Memory

527 The Memory hierarchy represents a memory device (or one of multiple devices). A Memory is  
528 represented as a collection of sensors.

## 529 5.8 Events

### 530 5.8.1 General

531 This model supports using PLDM events as a method to notify the MC upon changes in the sensor  
532 readings/states as described in [DSP2048](#). The following example events can be used with the model and  
533 the implementation may choose to have more events.

### 534 5.8.2 Accelerator firmware version change

535 This event indicates to the MC that the firmware version of the Accelerator has changed. The MC may  
536 use the *GetPDRRepositoryInfo* command and check if the *timestamp* parameter value has changed  
537 since it last read the PDRs. The MC may update the whole PDR repository by re-reading all the PDRs.  
538 The value used for the *timestamp* can be a virtual time value initialized by the Accelerator at device  
539 initialization.

### 540 5.8.3 Health and state sensors events notifications

541 The sensors on the accelerator card may report a change in value, health, or state using a PLDM state or  
542 numeric sensor event. Providing such a notification can significantly shorten the response time, compared  
543 to waiting for the MC to poll the sensors, for an occurrence that requires the MC to take an action such as  
544 increasing the airflow from a cooling fan.

## 545 **6 Model use example**

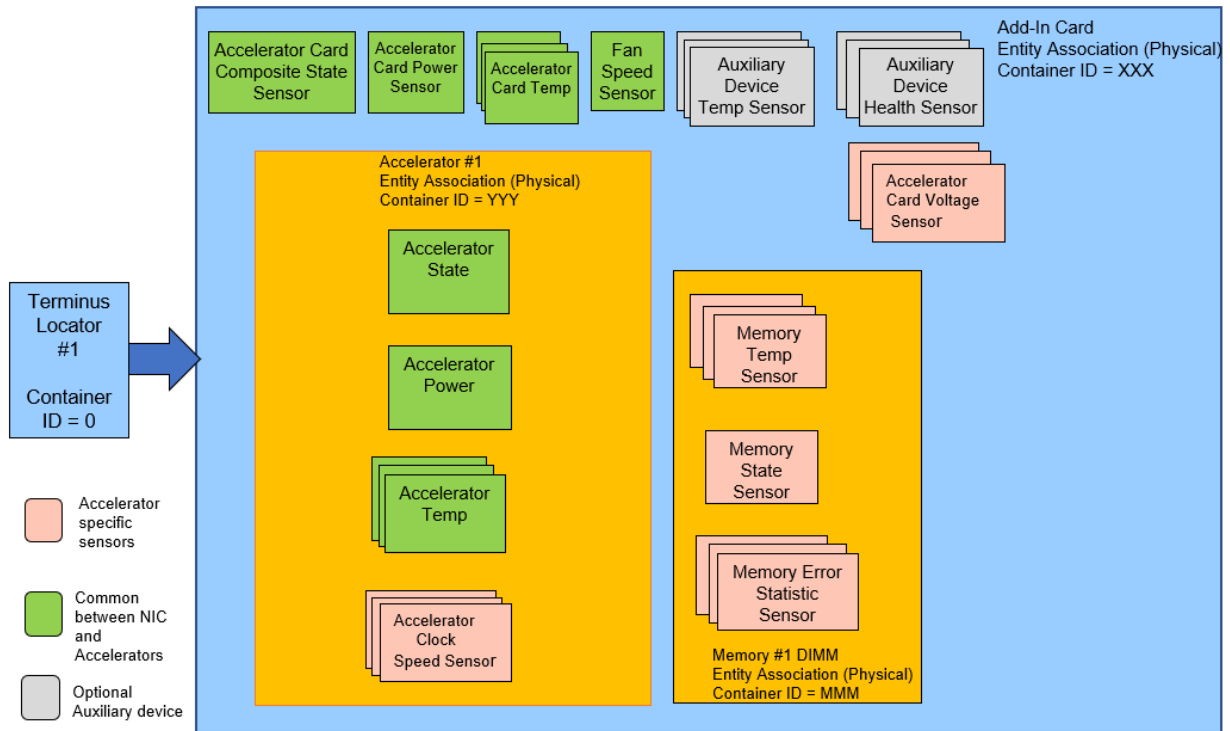
### 546 **6.1 General**

547 The following example for modeling an Accelerator card using PLDM for Platform Monitoring and Control  
548 [DSP0248](#) describes an Accelerator card with the following attributes:

- 549 • Accelerator Card
  - 550 ○ Temperature Sensor
  - 551 ○ State Sensor
  - 552 ○ Fan speed Sensor
  - 553 ○ Voltage Sensors
  - 554 ○ Power Sensor
  - 555 ○ Auxiliary Device Temperature Sensor
  - 556 ○ Auxiliary Device Health Sensor
- 557 • Accelerator
  - 558 ○ Temperature Sensor
  - 559 ○ Power Sensor
  - 560 ○ State Sensor
  - 561 ○ Clock speed Sensor
- 562 • Memory
  - 563 ○ Temperature Sensor
  - 564 ○ Memory State Sensor
  - 565 ○ Memory Error statistics Sensor

566 Figure 6 illustrates the model which is used in the example.

567



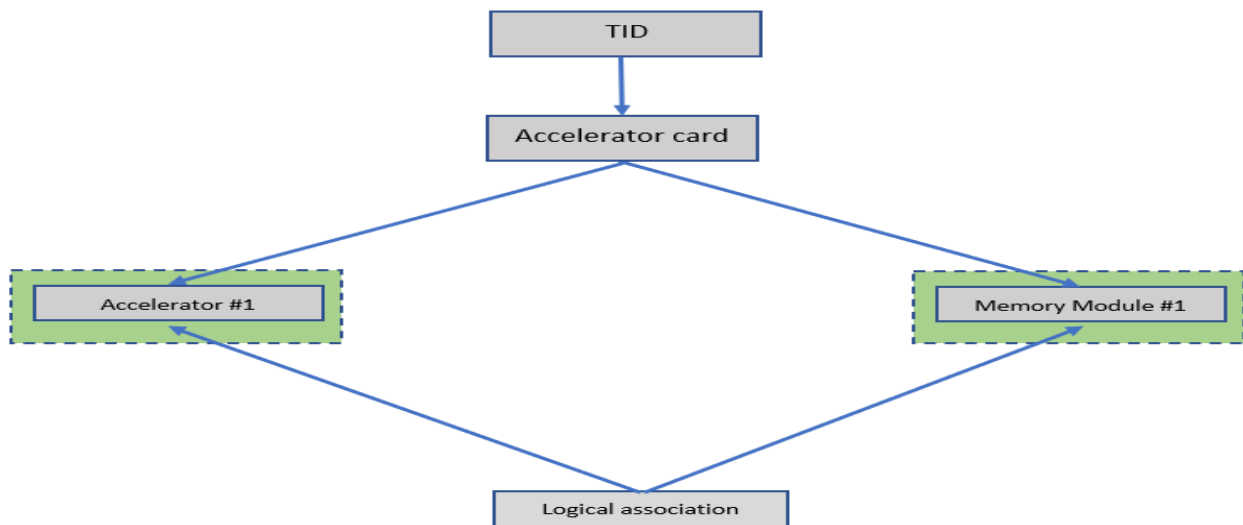
568

569

Figure 6 – Example model diagram

570 **6.2 Model hierarchy**

571 The model PDRs identify the elements depicted in Figure 6. The hierarchies are illustrated in the following  
 572 diagram. For simplicity, Figure 7 shows sensors of Accelerator and Memory Module.



573

574

Figure 7 – Accelerator card model hierarchy



575 **6.3 Top-level TID**

576 The terminus ID is identified by the terminus locator PDR. The TID defines the top-level entry point to the  
 577 PLDM model. Because there is only one Accelerator on the Accelerator card in this example, there is only  
 578 one TID.

579 **Table 4 – TID PDR**

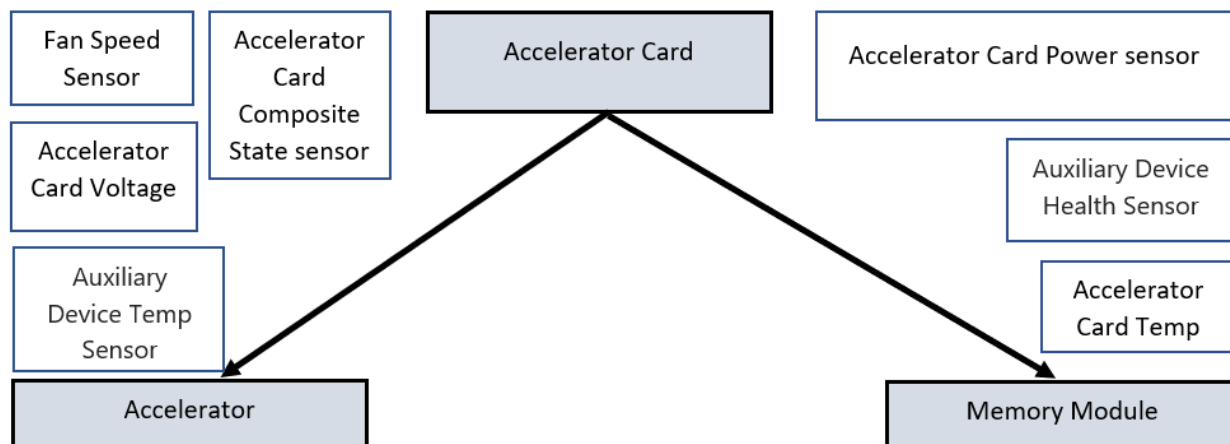
Field name	Value	Description
Container ID	0	System
TID		Assigned by MC
Record Handle	1100	Opaque number
Terminus Locator Size	1	Size of (EID) or size of (UID)
Terminus Locator Type	1	MCTP EID
EID	EID	MCTP assigned EID Value
UID	UID	Vendor provided UUID format value

580 The TID value is assigned to the terminus by the MC. When the transport layer is MCTP, the identification  
 581 of the terminus is performed using the Endpoint ID (EID) value. When using PLDM  
 582 over RBT, the terminus locator PDR shall use the UID (instead of EID). The UID value in the terminus  
 583 locator PDR uses the device UUID value as the terminus UID. For more information regarding terminus  
 584 locator PDR see [DSP0248](#)  
 585

586 **6.4 Accelerator card**

587 **6.4.1 General**

588 The top level of the model is the Accelerator card. The Accelerator card includes the physical elements  
 589 which are an Accelerator (only one Accelerator in this example) and a memory module (only one memory  
 590 module in this example).



591  
 592 **Figure 8 – Accelerator card level elements**

593 The sensors on the Accelerator card level are described using a reference to the measured entity,  
 594 independent of the container that includes all the physical elements on the Accelerator card.

595

Accelerator card Entity Association PDR		
Container ID	100	
Record Handle	1100	
Container Entity		
Entity Type	68	Add-In card
Entity Instance Number	1	
Container Entity Container ID	0	System
Association Type		
Association Type	Physical to Physical containment	
Contained Entity – Accelerator		
Entity Type	149	Accelerator
Entity Instance Number	1	
Contained Entity Container ID	100	Accelerator card
Contained Entity – Memory		
Entity Type	66	Memory
Entity Instance Number	1	
Contained Entity Container ID	100	Accelerator card

596

**Figure 9 – Accelerator card container PDR**

597  
598

**Note that the Accelerator card container ID, 100, is referenced by the sensors not included in the entity association PDR. The enumeration model shown in**

599  
600

Table 3 includes the container ID for every hierarchy level.

601 **6.4.2 Accelerator card power sensor**

602

Field	Value	Description
Record Handle	1102	
Sensor ID	6	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Base Unit	7	Watts
Unit Modifier	-1	0.1 watt resolution

603

**Figure 10 – Accelerator card power sensor PDR**

604 **6.4.3 Accelerator card temperature sensor**

605

Field	Value	Description
Record Handle	1130	
Sensor ID	20	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Base Unit	2	Degrees Celsius
Unit Modifier	0	No need for scaling

606

**Figure 11 – Ambient Temperature sensor PDR**

607 **6.4.4 Accelerator card fan speed sensor**

608

Field	Value	Description
Record Handle	1150	
Sensor ID	40	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Base Unit	19	RPM
Unit Modifier	0	No need for scaling

609

**Figure 12 – Accelerator card fan speed sensor PDR**

610 **6.4.5 Accelerator card voltage sensor**

611

Field	Value	Description
Record Handle	1170	
Sensor ID	80	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Base Unit	5	Volts
Unit Modifier	-1	0.1 volt resolution

612

**Figure 13 – Accelerator card voltage sensor PDR**

613 **6.4.6 Accelerator card auxiliary device temperature sensor**

614

Field	Value	Description
Record Handle	1395	
Sensor ID	380	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Base Unit	2	Degrees Celsius
Unit Modifier	0	No need for scaling

615

**Figure 14 – Auxiliary device temperature sensor PDR**

616 **6.4.7 Accelerator card auxiliary device health sensor**

617

Field	Value	Description
Record Handle	1400	
Sensor ID	395	
Entity Type	68	Add-In card
Entity Instance	1	Accelerator card Instance #
Container ID	0	System
Sensor Type	1	Health state
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

618

**Figure 15 – Auxiliary device health sensor PDR**

619 **6.4.8 Accelerator card composite state sensor**

620

Record Handle	1101	
Entity Type	68	Add-In card
Entity Instance Number	1	
Container Entity Container ID	0	System

Terminus Handle	0
Sensor ID	5
Composite Sensor Count	3

Sensor Type	1	Health state
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

Sensor Type	21	Thermal Trip
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

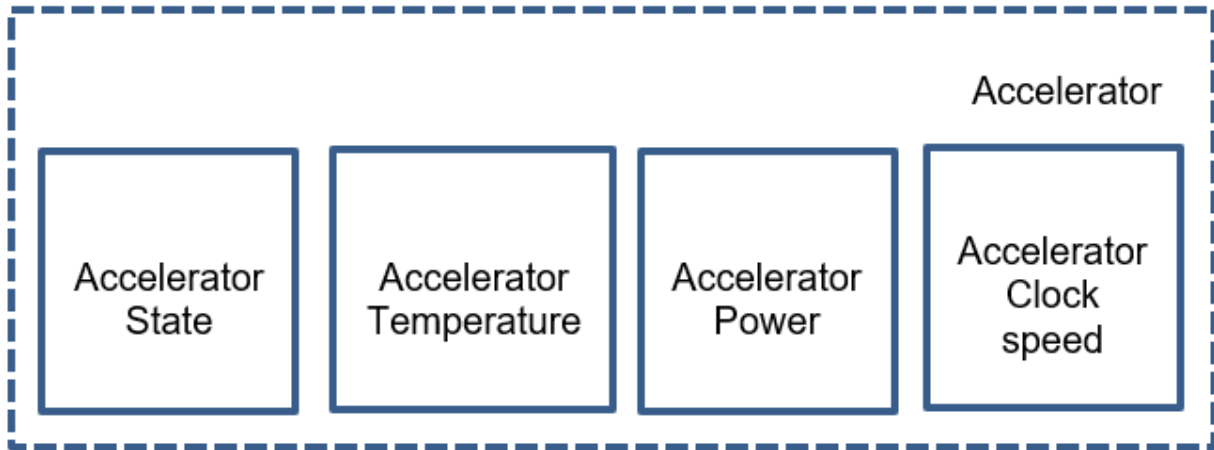
Sensor Type	10	Memory Operational Fault status
Possible States	Refer to Table 1 of DSP0249	

621 **Figure 16 – Accelerator card composite state sensor PDR**

622 **6.5 Accelerator**

623 **6.5.1 General**

624 The Accelerator is an active device and being a physical entity that doesn't include other entities, the  
 625 Accelerator is not declared in its own PDR. It is instead declared in the Accelerator card container PDR.  
 626 The Accelerator includes a set of device-level sensors. The following diagram illustrates the model  
 627 sensors in the Accelerator:



628

629

**Figure 17 – Example model Accelerator**

630 The Accelerator content is declared using an entity-association PDR that includes the hierarchical  
 631 description of the Accelerator. The device-level sensors are declared with separate PDRs using direct  
 632 references to the measured entities.

633

Container ID	1000
Record Handle	1295

Container Entity		
Entity Type	149	Accelerator
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

Association Type	Physical to Physical containment
------------------	----------------------------------

634

**Figure 18 – Accelerator entity association PDR**

635 **6.5.2 Accelerator temperature sensor**

636

Field	Value	Description
Record Handle	1325	
Sensor ID	240	
Entity Type	149	Accelerator
Entity Instance	1	Accelerator Instance #
Container ID	100	Accelerator card
Base Unit	2	Degrees Celsius

637

**Figure 19 – Accelerator temperature sensor PDR**

638 **6.5.3 Accelerator power sensor**

639

Field	Value	Description
Record Handle	1310	
Sensor ID	210	
Entity Type	149	Accelerator
Entity Instance	1	Accelerator Instance #
Container ID	100	Accelerator card
Base Unit	7	Watts
Unit Modifier	-1	0.1 watt resolution

640

**Figure 20 – Accelerator power sensor PDR**

641

642 **6.5.4 Accelerator composite state sensor**

643

Record Handle	1315	
Entity Type	149	Accelerator
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

Terminus Handle	0
Sensor ID	220
Composite Sensor Count	5

Sensor Type	1	Health state
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

Sensor Type	21	Thermal Trip
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

Sensor Type	18	Firmware Version
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

644

Sensor Type	15	Configuration
Possible States	Refer to Table 1 of DSP0249	

Sensor Type	16	Configuration Change
Possible States	Refer to Table 1 of DSP0249	

645

**Figure 21 – Accelerator composite state sensor PDR**

646



647 **6.5.5 Accelerator clock speed sensor**

648

Field	Value	Description
Record Handle	1335	
Sensor ID	260	
Entity Type	149	Accelerator
Entity Instance	1	Accelerator Instance #
Container ID	100	Accelerator Card
Base Unit	20	Hertz
Unit Modifier	6	1 MHz resolution

649

**Figure 22 – Accelerator card clock speed sensor PDR**

650 **6.6 Memory**

651 **6.6.1 General**

652 The Memory is a physical entity in the model. The Memory is already declared within the Accelerator card  
 653 container PDR. The Memory includes a set of device-level sensors. The Memory sensors cover all three  
 654 types of memory i.e., DIMM, Internal memory and soldered memory chips. The following diagram  
 655 illustrates the model sensors in the Memory:

656

657

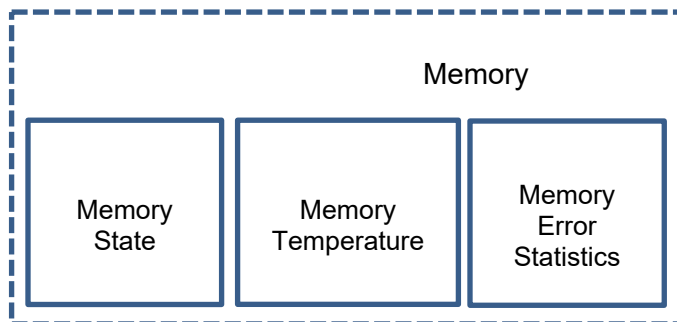
658

659

660

661

662



663

**Figure 23 – Example Memory model**

664 The Memory content is declared using an entity-association PDR that includes the hierarchical  
 665 description of the Memory. The device-level sensors are declared with separate PDRs using direct  
 666 references to the measured entities.

Container ID	1020
Record Handle	1210

Container Entity		
Entity Type	66	Memory
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

Association Type	Physical to Physical containment
------------------	----------------------------------

667 **Figure 24 – Memory association PDR**

668 **6.6.2 Memory temperature sensor**

669

Field	Value	Description
Record Handle	1225	
Sensor ID	125	
Entity Type	66	Memory
Entity Instance	1	Memory Instance #
Container ID	100	Accelerator card
Base Unit	2	Degrees C

670 **Figure 25 – Memory temperature sensor PDR**

671 **6.6.3 Memory error statistics sensors**

672

Field	Value	Description
Record Handle	1255	
Sensor ID	150	
Entity Type	66	Memory
Entity Instance	1	Memory instance #
Container ID	100	Accelerator card
Base Unit	80	Correctable Errors

673 **Figure 26 – Memory correctable errors PDR**

Field	Value	Description
Record Handle	1275	
Sensor ID	180	
Entity Type	66	Memory
Entity Instance	1	Memory Instance #
Container ID	100	Accelerator card
Base Unit	81	Uncorrectable Errors

674 **Figure 27 – Memory uncorrectable errors PDR**

675 **6.6.4 Memory composite state sensor**

676

Memory composite state sensor PDR		
Record Handle	1220	
Entity Type	66	Memory
Entity Instance Number	1	
Container Entity Container ID	100	Accelerator card

Terminus Handle	0
Sensor ID	120
Composite Sensor Count	4

Sensor Type	1	Health state
Possible States	Refer to Table 1 of <a href="#">DSP0249</a>	

Sensor Type	320	Memory cache status
Possible States	Refer to Table 11 of <a href="#">DSP0249</a>	

Sensor Type	321	Memory error status
Possible States	Refer to Table 11 of <a href="#">DSP0249</a>	

677

Sensor Type	322	Redundant Memory activity status
Possible States	Refer to Table 11 of <a href="#">DSP0249</a>	

678 **Figure 28 – Memory composite state sensor PDR**

679

680  
681  
682

## ANNEX A (informative) Notation and conventions

### 683 A.1 Notations

684 Examples of notations used in this document are as follows:

- 685 • 2:N In field descriptions, this will typically be used to represent a range of byte offsets  
686 starting from byte two and continuing to and including byte N. The lowest offset is on  
687 the left; the highest is on the right.
- 688 • (6) Parentheses around a single number can be used in message field descriptions to  
689 indicate a byte field that may be present or absent.
- 690 • (3:6) Parentheses around a field consisting of a range of bytes indicates the entire range  
691 may be present or absent. The lowest offset is on the left; the highest is on the right.
- 692 • [PCle](#) Underlined, blue text is typically used to indicate a reference to a document or  
693 specification called out in “Normative references” clause or to items hyperlinked within  
694 the document.
- 695 • rsvd This case-insensitive abbreviation is for “reserved.”
- 696 • [4] Square brackets around a number are typically used to indicate a bit offset. Bit offsets  
697 are given as zero-based values (that is, the least significant bit [LSb] offset = 0).
- 698 • [7:5] This notation indicates a range of bit offsets. The most significant bit is on the left; the  
699 least significant bit is on the right.
- 700 • 1b The lowercase “b” following a number consisting of 0s and 1s is used to indicate the  
701 number is being given in binary format.
- 702 • 0x12A A leading “0x” is used to indicate a number given in hexadecimal format.

703

704  
705  
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## ANNEX B (informative)

### Change log

Version	Date	Description
1.0.0	5/25/2022	Initial draft
1.0.0	6/13/2023	Released for publication

709